









PRODUCT DATASHEET



- ► PTH/THT Lamp
- ▶ 8mm Round 11.0t
- ► Red (637nm)

NOR37L00





APPLICATIONS:

- Indicator
- Signal
- 3C Application

8mm Round Lamp Compliant





Release Date: 13 December 2023 Version: A1.1

FEATURES:

- Package: PTH/THT LED Lamp 8mm Round 11.0t
- Forward Current: 20mA Forward Voltage (typ.): 1.9V
- Luminous Intensity (typ.): 300mcd@20mA
- Colour: Red
- Dominant Wavelength (typ.): 637nm
- Viewing Angle: 50°
- **Materials:**
 - Die: AllnGaP
 - Resin: Epoxy (Red Diffused) Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **Grouping Parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant wavelength
- Soldering Methods: Hand; Soldering Heat (DIP)
- Packing: max.500pcs/bulk



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

| Parameter | Symbol Ratings | | Unit |
|-------------------------------------|------------------|----------|------|
| Forward Current | IF | 30 | mA |
| Peak Forward Current Duty 1/10@1KHz | I _{FP} | 100 | mA |
| Reverse Current @5V | I _R | 10 | μА |
| Reverse Voltage | V _R | 5 | V |
| Power Dissipation | P _D | 85 | mW |
| Operating Temperature | TOPR | -40~+85 | °C |
| Storage Temperature | T _{STG} | -40~+100 | °C |

Electrical & Optical Characteristics (Ta=25°C)

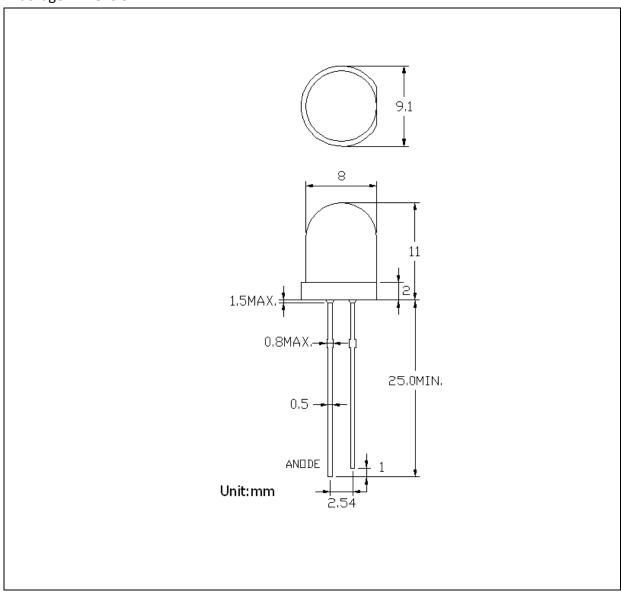
| Parameter | Cumbal | Values | | | Unit | Test |
|---------------------------------|-----------------------|--------|------|------|------|----------------------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Condition |
| Forward Voltage | V _F | 1.7 | 1.9 | 2.4 | V | I _F =20mA |
| Luminous Intensity | lv | 180 | 300 | 450 | mcd | I _F =20mA |
| Dominant Wavelength | λ_{D} | 632 | 637 | 643 | nm | I _F =20mA |
| Peak Wavelength | $\lambda_{	extsf{P}}$ | | 653 | | nm | I _F =20mA |
| Spectral Line Half Bandwidth | Δλ | | 19 | | nm | I _F =20mA |
| Viewing Angle | 2θ _{1/2} | | 50 | | deg | I _F =20mA |

^{1.} Luminous intensity (Iv) $\pm 15\%$, Forward Voltage (V_F) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$



OUTLINE DIMENSION:

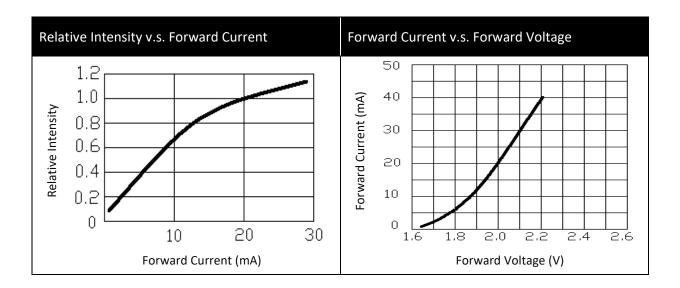
Package Dimension:

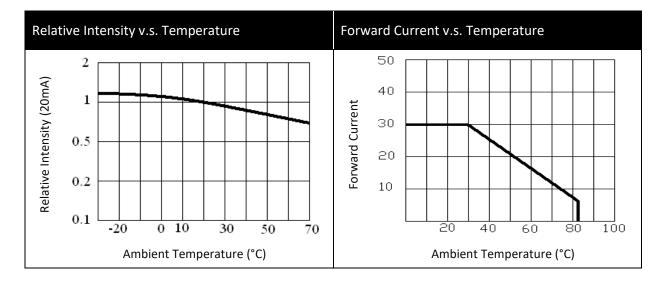


- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



ELECTRO-OPTICAL CHARACTERISTICS:





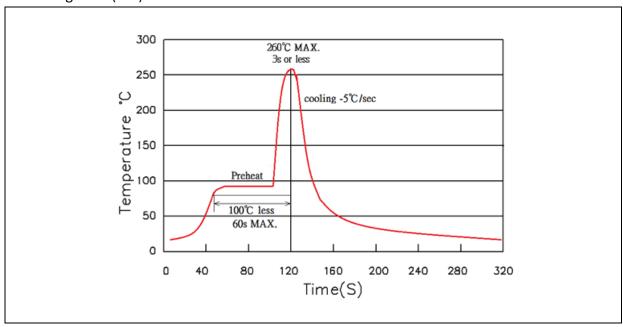


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

Soldering Heat (DIP):



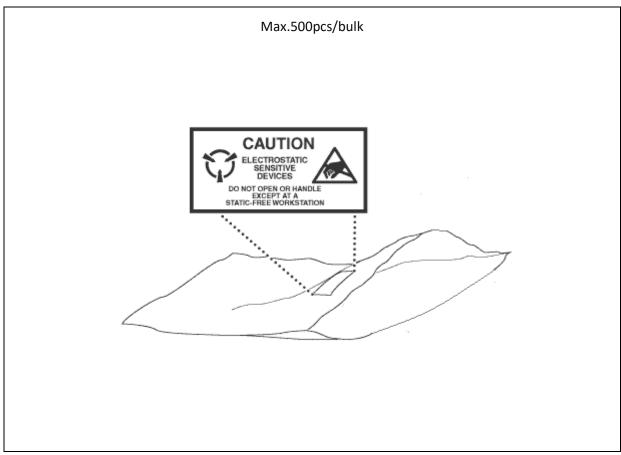
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a year. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

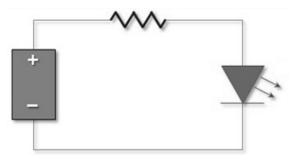
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

| Version | Date | Summary of Revision |
|---------|------------|---------------------------|
| A1.0 | 05/04/2023 | Datasheet set-up. |
| A1.1 | 13/12/2023 | Revise storage condition. |